

METHOD FOR PROCESSING MULTIPLE SEMICONDUCTOR DEVICES FOR TEST

Abstract of the Disclosure

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A packaged array (10) having a temporary substrate (20) is used to test a plurality of semiconductor devices (14). In one embodiment, the temporary substrate (20) is an adhesive substrate, such as tape. A support structure (18) may lie over the temporary substrate (20) or be within the temporary substrate (20). The plurality of semiconductor devices (14) lie within an array (16, 6, or 8) and may be tested in parallel. One array or a multiple number of arrays may lie on the packaged array (10).